

1. General description

Ultrafast power diode in 2-leads TO-262 (I2PAK) plastic package.

2. Features and benefits

- Low forward voltage drop
- Low leakage current
- Soft reverse recovery characteristics
- High thermal cycling performance

3. Applications

- Home appliance power supply
- Discontinuous Current Mode (DCM) Power Factor Correction (PFC)

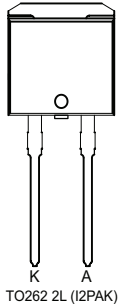
4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Values				Unit
Absolute maximum rating							
V _{RRM}	repetitive peak reverse voltage		600				V
I _{F(AV)}	average forward current	δ = 0.5 ; square-wave pulse; T _{mb} ≤ 150 °C; Fig. 1 ; Fig. 2 ; Fig. 3	9				A
I _{FRM}	repetitive peak forward current	δ = 0.5 ; t _p = 25 μs; T _{mb} ≤ 150 °C; square-wave pulse	18				A
I _{FSM}	non-repetitive peak forward current	t _p = 10 ms; T _{j(init)} = 25 °C; sine-wave pulse; Fig. 4	120				A
		t _p = 8.3 ms; T _{j(init)} = 25 °C; sine-wave pulse;	132				A
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward voltage	I _F = 8 A; T _j = 25 °C; Fig. 6		-	1.05	1.3	V
		I _F = 8 A; T _j = 150 °C; Fig. 6		-	0.9	1.1	V
Dynamic characteristics							
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 7		-	40	75	ns

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode		
2	A	anode		
mb	mb	mounting base; connected to cathod		

6. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
BYV29G-600P	TO-262	Plastic single-ended package(I2PAK); 2 leads TO-262	I2PAK

7. Marking

Table 4. Marking codes

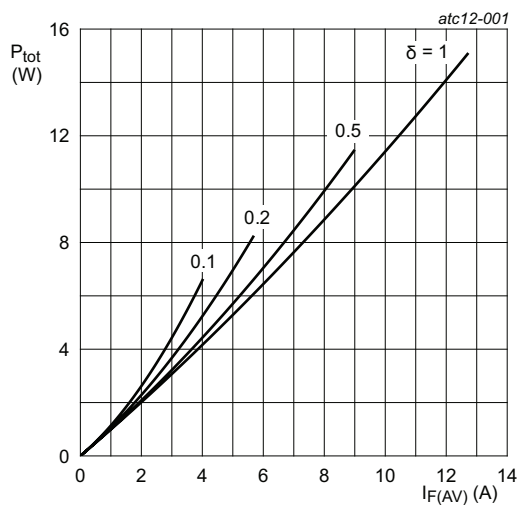
Type number	Marking codes
BYV29G-600P	BYV29G-600P

8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

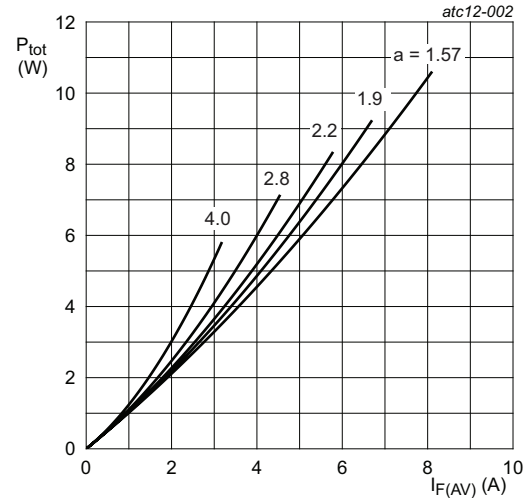
Symbol	Parameter	Conditions	Values	Unit
V_{RRM}	repetitive peak reverse voltage		600	V
V_{RWM}	crest working reverse voltage		600	V
V_R	reverse voltage	DC	600	V
$I_{F(AV)}$	average forward current	$\delta = 0.5$; square-wave pulse; $T_{mb} \leq 150\text{ }^{\circ}\text{C}$; Fig. 1 ; Fig. 2 ; Fig. 3	9	A
I_{FRM}	repetitive peak forward current	$\delta = 0.5$; $t_p = 25\text{ }\mu\text{s}$; $T_{mb} \leq 150\text{ }^{\circ}\text{C}$; square-wave pulse	18	A
I_{FSM}	non-repetitive peak forward current	$t_p = 10\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse; Fig. 4	120	A
		$t_p = 8.3\text{ ms}$; $T_{j(\text{init})} = 25\text{ }^{\circ}\text{C}$; sine-wave pulse;	132	A
T_{stg}	storage temperature		-55 to 175	$^{\circ}\text{C}$
T_j	junction temperature		175	$^{\circ}\text{C}$



$$I_{F(AV)} = I_{F(RMS)} \times \sqrt{\delta}$$

$$V_o = 0.973\text{ V}; R_s = 0.0168\text{ }\Omega$$

Fig. 1. Forward power dissipation as a function of average forward current; square waveform; maximum values



$$a = \text{form factor} = I_{F(RMS)} / I_{F(AV)}$$

$$V_o = 0.973\text{ V}; R_s = 0.0168\text{ }\Omega$$

Fig. 2. Forward power dissipation as a function of average forward current; sinusoidal waveform; maximum values

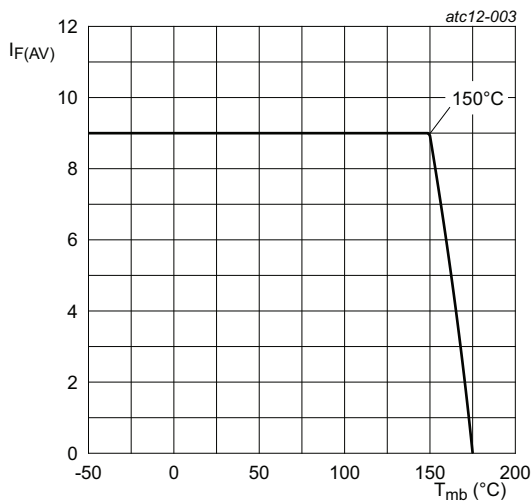


Fig. 3. Forward current as a function of mounting base temperature; maximum values

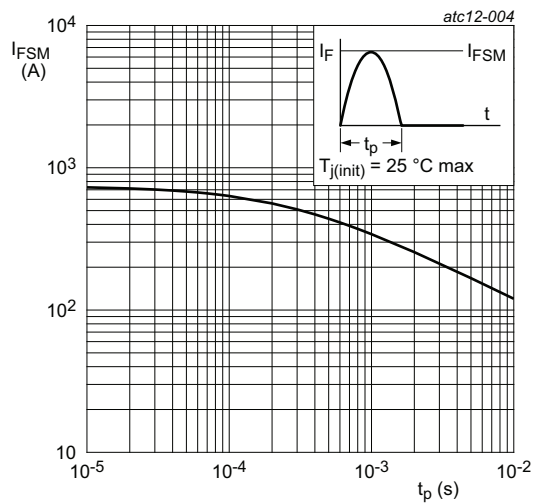


Fig. 4. Non-repetitive peak forward current as a function of pulse width; sinusoidal waveform; maximum values

9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 5	-	-	2.2	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient free air	in free air	-	55	-	K/W

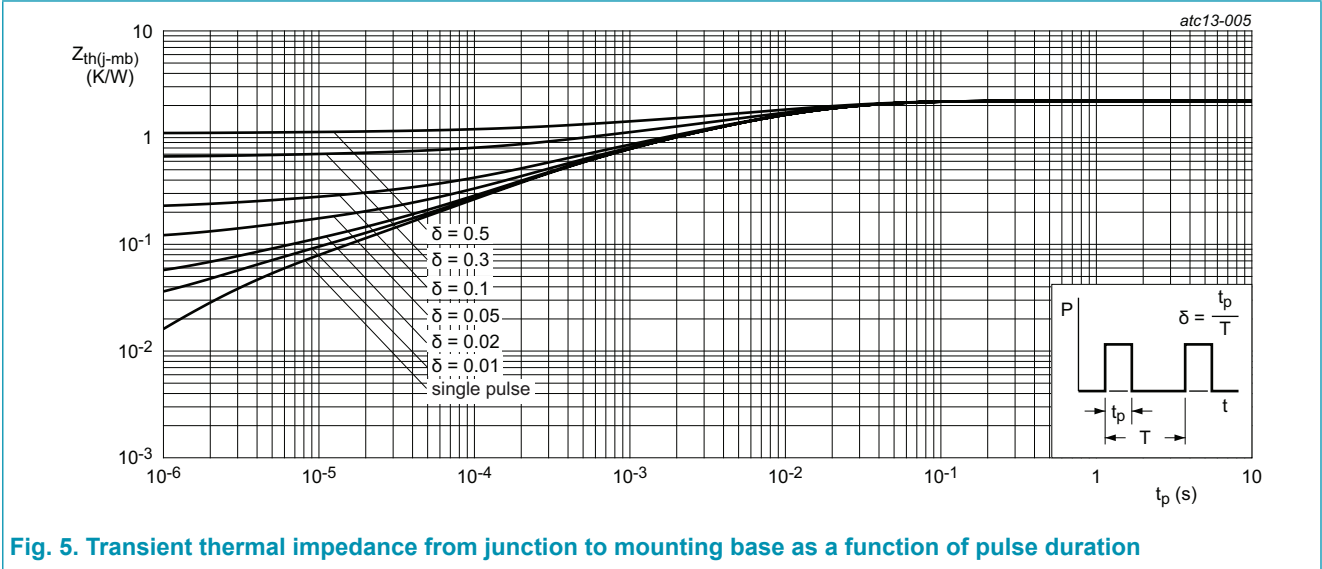
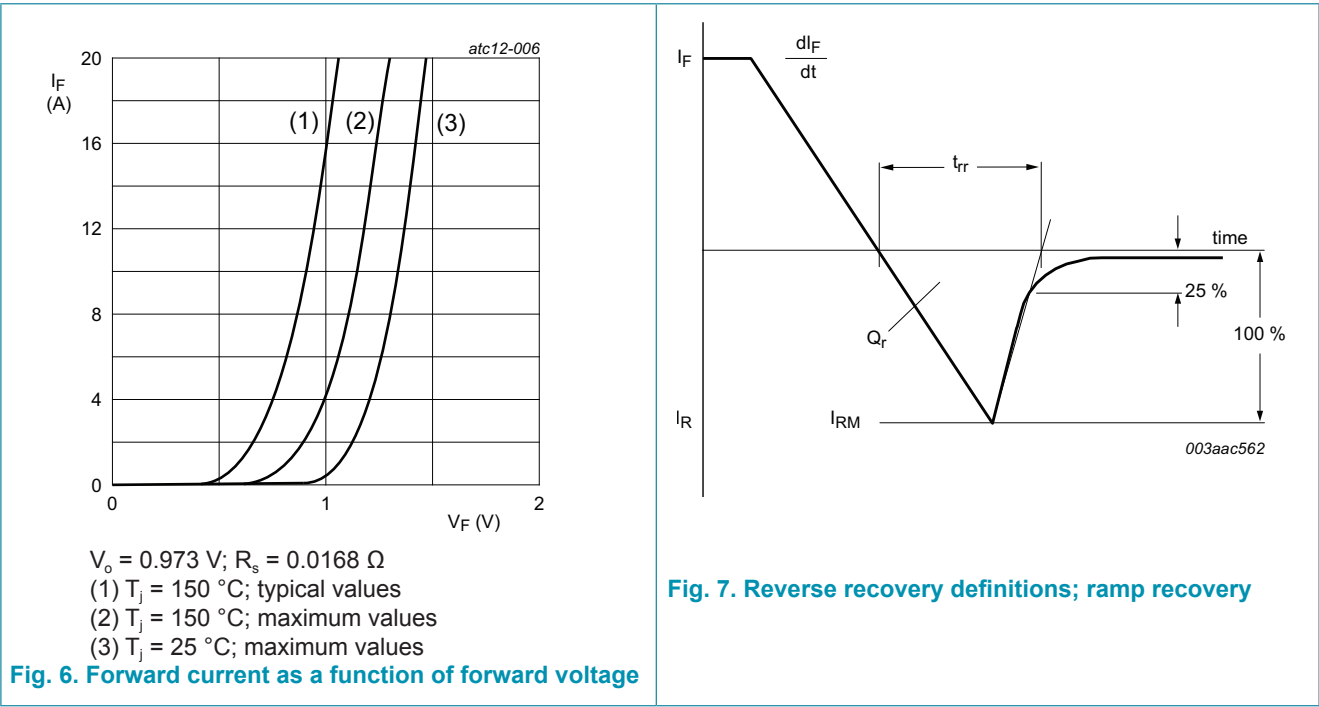


Fig. 5. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

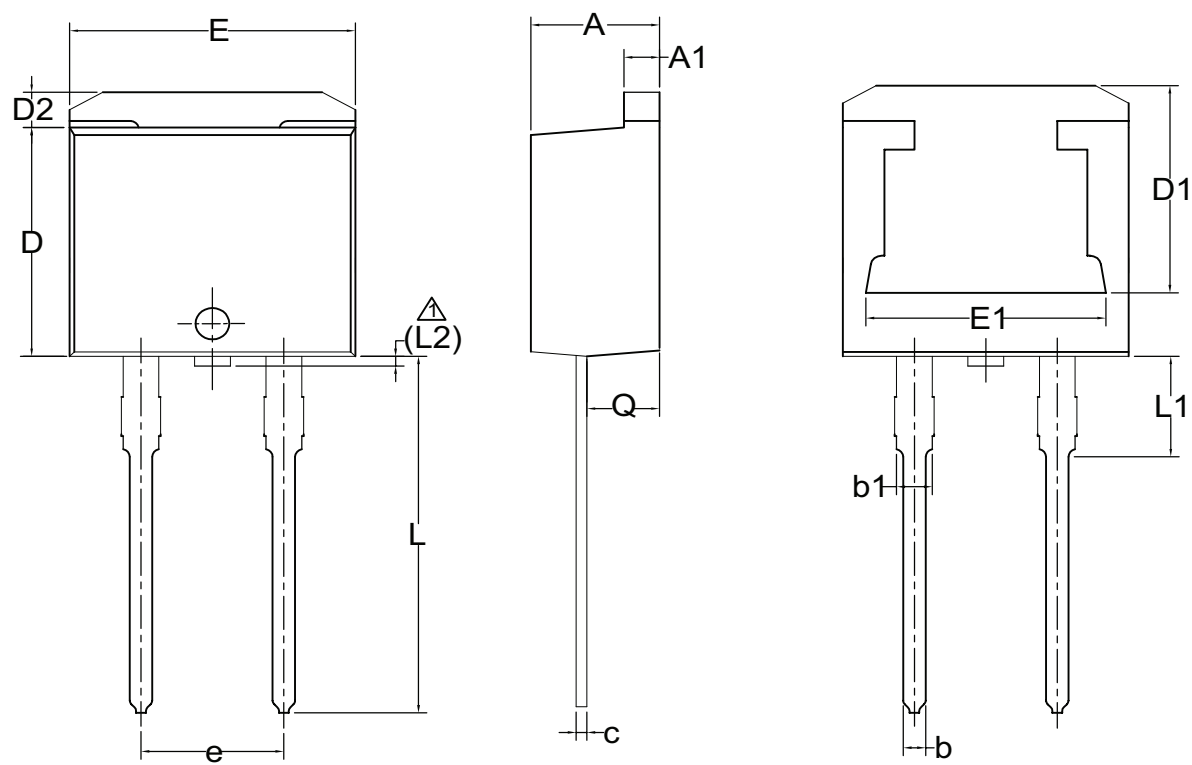
Symbol	Parameter	Conditions		Min	Typ	Max	Unit
Static characteristics							
V _F	forward current	I _F = 8 A; T _j = 25 °C; Fig. 6		-	1.05	1.3	V
		I _F = 8 A; T _j = 150 °C; Fig. 6		-	0.9	1.1	V
I _R	reverse current	V _R = 600 V; T _j = 25 °C		-	-	10	μA
		V _R = 600 V; T _j = 150 °C		-	-	0.4	mA
Dynamic characteristics							
Q _r	reverse charge	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 7		-	55	-	nC
t _{rr}	reverse recovery time	I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 7		-	40	75	ns
I _{RM}	peak reverse recovery current	I _F = 1 A; V _R = 30 V; dI _F /dt = 50 A/μs; T _j = 25 °C; Fig. 7		-	1.9	-	A
		I _F = 1 A; V _R = 30 V; dI _F /dt = 100 A/μs; T _j = 25 °C; Fig. 7		-	2.8	-	A



11. Package outline

Plastic single-ended package(I2PAK);2 leads TO-262

TO262-2L



Unit	A	A1	b	b1	c	D	D1	D2	E	E1	e	L	L1	L2	Q
MM	min	4.35	1.14	0.69	1.14	0.36	8.50	7.50	1.00	10.00	8.25	13.00	3.40		2.40
	max	4.75	1.40	1.01	1.73	0.61	9.02	8.00	1.65	10.40	8.89	14.00	3.80	0.35	2.80

Notes:
△ L2 protrusion is the mold resin.

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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